

IV. AMENDMENTS TO THE CLAIMS

1. (CURRENTLY AMENDED) ~~A~~ The semiconductor device according to claim 7, further comprising:
a semiconductor chip having an active surface and an inactive surface disposed opposite the active surface;
protective resin covering a sidewall of the semiconductor chip and having a surface formed so as to be flush with the inactive surface of the semiconductor chip;
~~_____~~ a board having a surface on which the semiconductor chip is mounted and an opposite surface; and
an external connecting terminal permanently joined to ~~a~~ an opposite surface of the board that is facing away from the semiconductor chip, the external connecting terminal being electrically connected to the active surface of the semiconductor chip;
wherein the protective resin is permanently joined to the surface of the board and the external connecting terminal is permanently joined at the opposite surface of the board.

2. (CURRENTLY AMENDED) The semiconductor device according to claim 1, further comprising an interconnection terminal electrically connected to the active surface of the semiconductor chip ~~and having an exposed portion exposed to the outside of the protective resin~~, the interconnection terminal being joined to the active surface of the semiconductor chip and to ~~a~~ the mounting surface of the board that is facing to the semiconductor chip, the external terminal being electrically connected to the active surface of the semiconductor chip via the interconnection terminal.

3. - 6. (CANCELED).

7. (CURRENTLY AMENDED) A semiconductor device, comprising:
a board having a mounting surface and an opposite surface;
a semiconductor chip mounted on the mounting surface of the board.

~~the semiconductor chip having an active surface and an inactive surface which is a surface on the opposite side of disposed opposite the active surface, the semiconductor chip being joined to the board in a state where the active surface thereof is facing to the board and the inactive surface thereof is exposed; and~~

~~a protective resin permanently joined to the mounting surface of the board covering a sidewall of the semiconductor chip with the inactive surface thereof exposed to the outside of the protective resin, and having a surface formed so as to be flush with an inactive surface of the semiconductor chip; and having a side surface formed so as to be flush with a side surface of the board along a plane perpendicular to the mounting surface of the board~~

~~an external connecting terminal joined to a surface of the board that is facing away from the semiconductor chip, the external connecting terminal being electrically connected to the active surface of the semiconductor chip;~~

~~wherein the protective resin is permanently joined to the mounting surface of the board and the external connecting terminal is permanently joined at the opposite surface of the board.~~

8. (ORIGINAL) The semiconductor device according to claim 7, wherein the board is a wiring board having a wiring pattern formed therein.

9. – 20. (CANCELED).

21. (NEW) A semiconductor device, comprising:
a board having a mounting surface and an opposite surface;
a first semiconductor chip mounted on the mounting surface of the board, the first semiconductor chip having an active surface and an inactive surface disposed opposite the active surface, the first semiconductor chip being joined to the board in a state where the inactive surface thereof is facing to the board;
a second semiconductor chip having an active surface and an inactive surface disposed opposite the active surface, the second semiconductor chip being joined to the first semiconductor chip in a state where the active surface of the second semiconductor chip is facing to the active surface of the first semiconductor chip;

bonding wires connecting the active surface of the first semiconductor chip and the mounting surface of the board;

a protective resin, permanently joined to the mounting surface of the board, covering the bonding wires and sidewalls of the first and second semiconductor chips with the inactive surface of the second semiconductor chip exposed to the outside of the protective resin, the protective resin having a surface formed so as to be flush with the inactive surface of the second semiconductor chip.

22. (NEW) The semiconductor device according to claim 21, wherein the protective resin has a side surface formed so as to be flush with a side surface of the board along a plane perpendicular to the mounting surface of the board.

23. (NEW) A semiconductor device, comprising:
a semiconductor chip having an active surface and an inactive surface disposed opposite the active surface;
a lead frame having an exposed portion for external connection;
a bonding wire connecting the active surface of the semiconductor chip and the lead frame;
a protective resin covering a sidewall of the semiconductor chip, the lead frame and the bonding wire, the inactive surface of the semiconductor chip being exposed to the outside of the protective resin, the exposed portion of the lead frame being exposed to the outside the protective resin, the protective resin having a first surface formed so as to be flush with the inactive surface of the semiconductor chip and a second surface, opposite the first surface, formed so as to be flush with a surface of the exposed portion of the lead frame.